



GAU 1753

**PATENT**  
(5298-03500/PM99021)

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of:  
Lau

Serial No. 09/476,669

Filed: December 30, 1999

For: **METHOD FOR FORMING A  
METALLIZATION STRUCTURE  
IN AN INTEGRATED CIRCUIT**

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Group Art Unit: 1753  
Examiner: Cantelmo, G.

Atty. Dkt. No. 5298-03500

I hereby certify that this correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231, on the date indicated below:

January 12, 2001  
Date

  
Kevin L. Daffer

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5/w.m.  
2/6/01

**RESPONSE TO OFFICE ACTION MAILED DECEMBER 12, 2000**

**Box: Non-Fee Amendment**  
Commissioner for Patents  
Washington, D.C. 20231

Dear Sir/Madam:

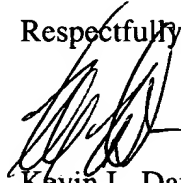
In the Office Action of December 12, 2000 for the above-captioned application, restriction was lodged in connection with the following groups: Group I claims 1-18 drawn to a method for fabricating a metallization structure, and Group II claims 19-20 drawn to a metallization structure.

Responsive to this restriction, Applicants hereby elect without traverse Group I claims 1-18. Applicants reserve the right to file a divisional application at a later date capturing the subject matter recited in non-elected Group II claims 19-20. If the Examiner has any questions, comments or suggestions, the undersigned attorney earnestly requests a telephone conference.

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TECHNOLOGY CENTER 1100

No fees are required for filing this amendment; however, the Commissioner is authorized to charge any additional fees which may be required, or credit any overpayment, to Conley, Rose & Tayon, P.C. Deposit Account No. 50-1505/5298-03500/KLD.

Respectfully submitted,



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Date: January 12, 2001  
GEC